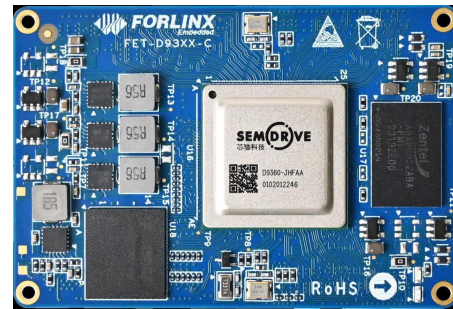


## FET-D9360-C SoM

FET-D9360-C system on module is powered by SemiDrive’s D9-Pro application processor that consists of 6 Cortex-A55 and 1 Cortex-R5. The SoM is based on 10-layer ENIG PCB with 44x 65mm, and it could be connected to carrier board via 4 ultra thin 4x 100-pin connectors which can maximize the processor’s power. Besides, the designing is compatible with all D9 series processors.



### Highlights:

- R5 core for real-time tasks processing;
- 16nm processing technology;
- Connection between SoM and carrier board based on four ultra thin 100-pin connectors, combined height only 1.5mm;
- Multiple high-speed peripherals, such as dual Gigabit Ethernet supported with TSN, USB3.0, CAN-FD, UART, etc;
- Supports dual LVDS displays, dual MIPI-CSI and triple-displaying;
- 3D GPU, AI accelerator and H.264 coder

6x Cortex-A55	2.0GHz	Cortex-R5
Architecture	Clock	Dual-core lock-step
16	4	-40~+85°C
UART	CAN-FD	Operating temp

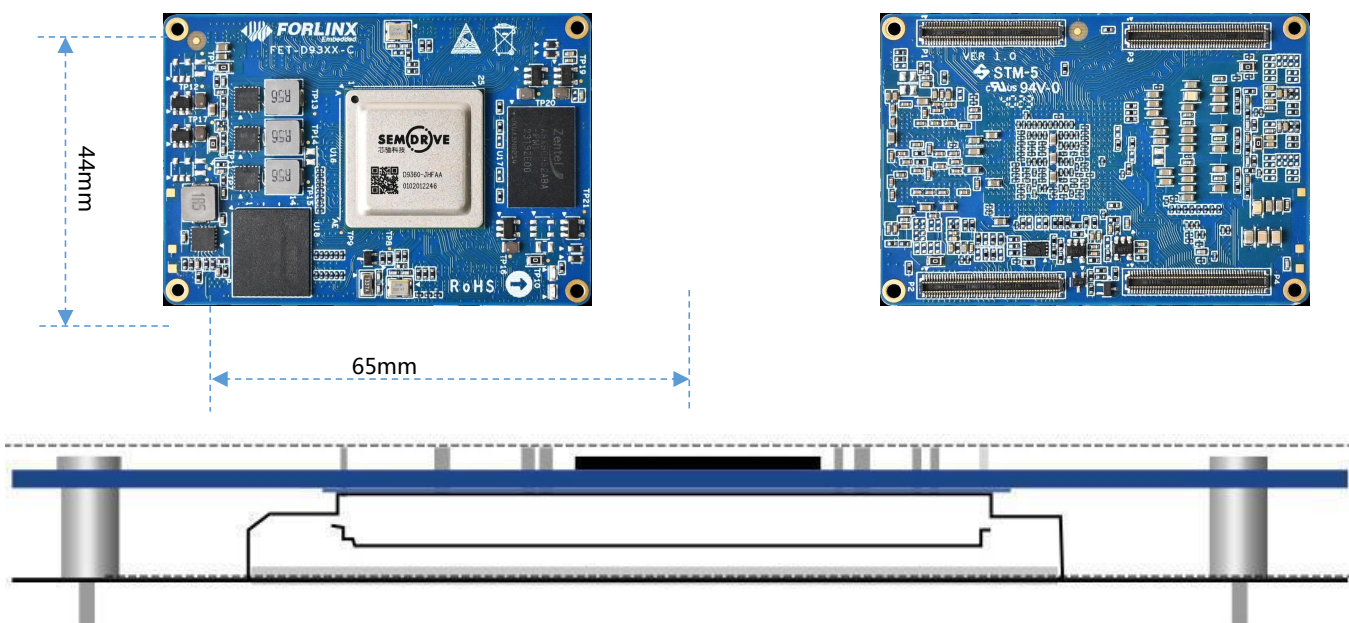
### SoM features :

CPU	<a href="#">SemiDrive D9 Pro</a> <b>CPU:</b> D9360-JHFAA <b>Architecture:</b> 6×Cortex-A55+1×Cortex-R5 <b>Clock:</b> 2.0GHz+ 800MHz <b>NPU:</b> 0.4TOPS INT8(0.8TOPS INT4) <b>GPU:</b> PowerVR 9XM 3D GPU, 100GFLOPS <b>VPU:</b> H.264 video codec, 4Kp30, H.265 video decoding 4Kp30
RAM	2GB/4GB LPDDR4x
ROM	16GB/32GB eMMC
Voltage input	DC 12V
Operating temp	-40°C~+85°C
Package	Board-to-board connector(4x 100-pin, pitch 0.4mm, combined height 1.5mm)

## SoM specifications:

Peripheral	NUM	Spec.
LVDS	2	2x 8-lane dual LVDS, up to 2K; 4x 4-lane single LVDS, up to 1080P
MIPI-DSI	2	Up to 2K, fit with Forlinx 7" MIPI-DSI module(1024x 600)
MIPI-CSI	2	Supports 4 analog camera Supports 4 1080P@ 30FPS camera input
Ethernet	2	2x RGMII GMAC, rating 10/ 100/ 1000Mbps Supports 1.8V/ 2.5V RGMII mode Supports 3.3V RMII mode
PCIe	2	2x PCIe 3.0x1(or 1x PCIe3.0x2), supports RC/ EP
USB3.0	2	
CAN-FD	4	
OSPI	2	Supports SDR and DDR modes Supports data bit width defining, and supports 1bit/2bit/4bit/8bit mode
SDIO	2	Supports DS and HS Supports SDR 12/SDR 25/SDR 50/SDR 104/DDR 50
IIS	≤6	Supports 4 single channel I2S/ TDM, supports multiple data align mode; Supports 2 multi-channel I2S and multiple data align mode
ADC	4	12bit SAR ADC
SPI	≤8	Both host mode and slave mode are supported
UART	≤16	
IIC	≤12	
JTAG	1	

## Exterior and dimensions:



Note: tolerance  $\pm 0.2\text{mm}$

It's suggested to use double-pass copper pillars with M2\* 5mm, and mating screw with M2\* 4mm

## ■ OS:

<b>OS version</b>	Linux 4.14.61+Qt 5.15.2
<b>Firmware installation</b>	<ul style="list-style-type: none"> <li>• TF card</li> <li>• USB device</li> </ul>

## ■ Driver list:

	Peripheral	Function	Chipset
Linux5.4.61	SDIO	WiFi	AW-CM358
	UART	BT	
	I2S	Audio	NAU8822, 24bit, audio record: 8K-48K, playback 8K-96K
	I2C	RTC	PCF8563
	MIPI-DSI	7''	FIT-LCD7.0_MIPI V2.1, 1024×600, TP: FT3427
	LVDS	10.1''	IT_LVDS_10.1_C, 1280×800, TP: GT928
	USB	4G modem	EM05, M.2
	USB	5G modem	RM500U, RM500Q, M.2
	USB	USB to 4x UART	USB-TO-4-UARTS
	PCIe	NIC	INTEL E1000, 1000M wired NIC
	MIPI-CSI	camera	YT8521S
RGMII	Ethernet		

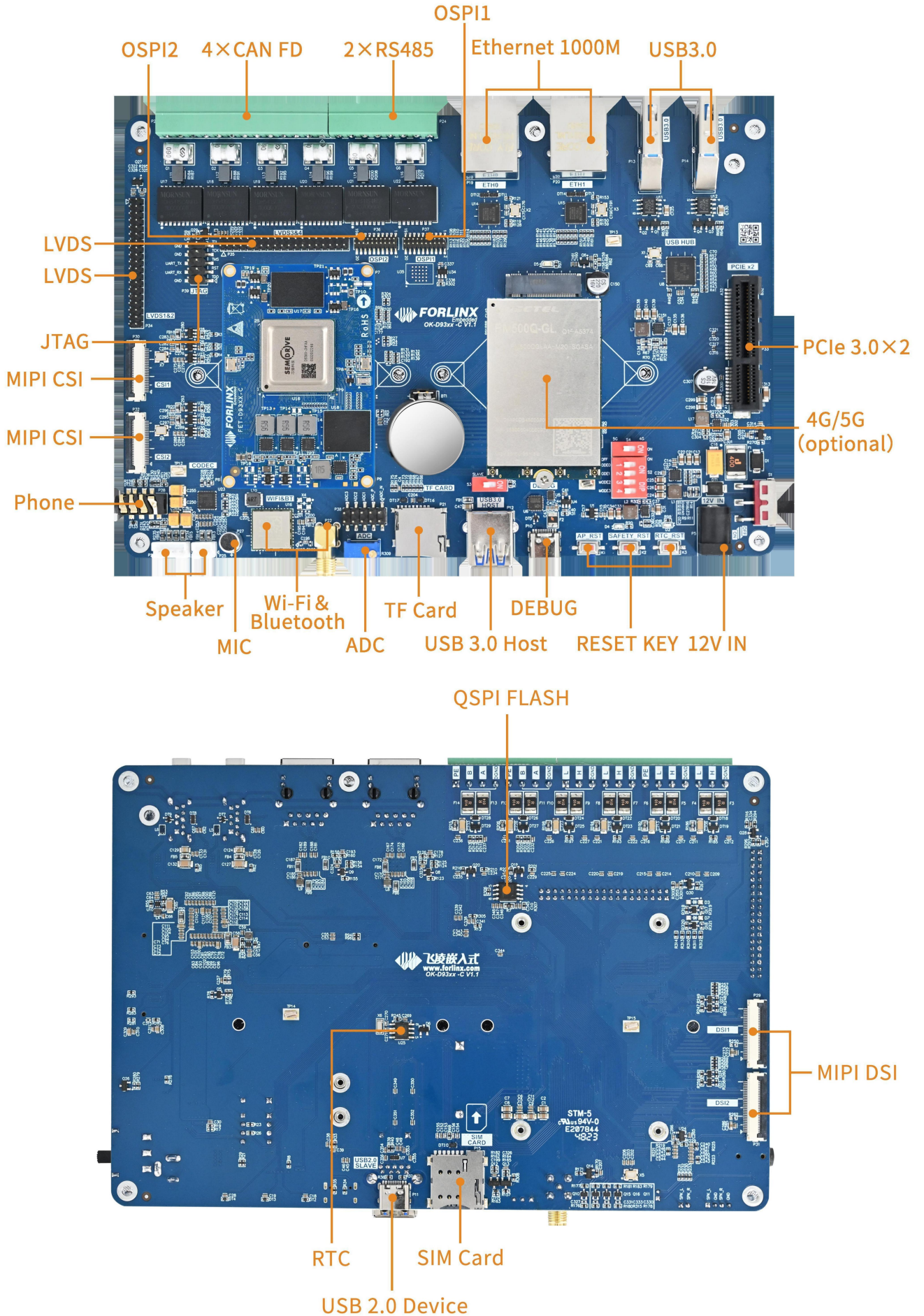
## ■ Provided technical files

<b>Linux4.14.61</b>	User manual, compiling guideline, GIT source, 3P tool and lib, reference files from StarFive, kernel source code, file system, OS image, VM ubuntu image, SD card making tool
<b>Hardware</b>	User manual, carrier board schematic, carrier board PCB(CAD), datasheet, carrier board and SoM DXF files, pinmux sheet

## ■ Ordering options:

Model	Core Number	Clock	RAM	Flash	Working temp	Phase
D9360-C+202GSE16GIA11: xx-x	6×A55	2.0GHz	2GB	16GB	-40~+85℃	Mass production
D9360-C+204GSE32GIB11: xx-x	6×A55	2.0GHz	4GB	32GB	-40~+85℃	Mass production

## Development board/ kit



## Carrier board features

Peripheral	NUM	Spec.
USB3.0	4	1 separate high-speed USB3.0 Type-A connector The carrier board is configured with one USB HUB for extra 3 USB3.0 expanding, 2 of them connected to USB3.0 Type-A, and 1 connected to M.2 B-KEY slot for 4G/ 5G
USB Device	1	USB 2.0 Device Type-C(up to 480Mbps), it shares one USB2.0 with USB3.0 Type-A for OS image flashing
4G/ 5G	1	1 M.2 B-KEY slot is available on carrier board for 4G/ 5G
Ethernet	2	10/100/1000Mbps, RJ45
Audio	1	On-board NAU88C22YG; Supports earphone output and MIC input, they are integrated into one 3.5mm jack; Supports 2 1W 8Ω speaker output, available on carrier board by XH2.54 white headers
MIPI-DSI	2	2x 4-lane MIPI-DSI are available on carrier board by FPC connector Fit with Forlinx 7" MIPI-DSI module with resolution of 1024x 600
MIPI-CSI	2	2x 4-lane MIPI-CSI are available on carrier board, OV5645 could be well supported
PCIe	1	1x PCIe3.0 x4 slot, only available for PCIe3.0 x1 or PCIe3.0 x2 device
LVDS	2	2x LVDS by headers with pitch of 2.0mm are available, can support below two solutions 2x 8-lane LVDS, each one up to 1080P; 4x 4-lane LVDS, each one up to 720P
CAN-FD	4	Isolated, CAN-FD is well supported and available on carrier board by DG128 terminal
RS485	2	Isolated
WiFi	1	Model: AW-CM358 IEEE 802.11a/b/g/n/ac WLAN with Bluetooth 5.2 Combo LGA Module
BT	1	WiFi is based on SDIO 3.0; BT is based on UART
TF Card	1	SD, SDHC, SDXC(UHS-I)
OSPI	2	Pin headers with pitch of 1.27mm
I2C	4	For carrier board audio, RTC, camera, TP and other related devices
PWM	5	For backlight control
ADC	4	By 2.54mm pin headers, SDC-CH4 is connected with a sliding rheostats
JTAG	1	By 2.54mm pin headers
RTC	1	
UART Debug	3	On-board USB to UART chip, for A55 serial debug and R5 debug
USB Debug	1	USB type-C port, default baud rate 115200

## Power Consumption

No.	Testing	Power input	SoM Consumption(w)	Evk Consumption(w)
1	Boot without loading, peak	12±5%	6.05	8.2
2	Standby mode, no loading	12±5%	4.38	6.45
3	CPU+ RAM+ eMMC stress testing	12±5%	6.2	8.3
4	2x 10.1" LVDS+OV5645+7" MIPI-DSI+ video decoding	12±5%	/	18
5	2x 10.1" LVDS+OV5645+7" MIPI-DSI +video encoding	12±5%	/	17.7